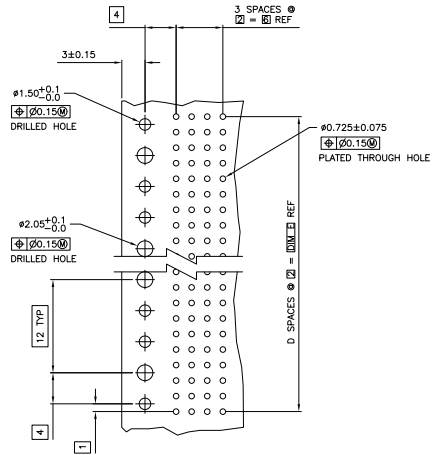
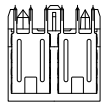
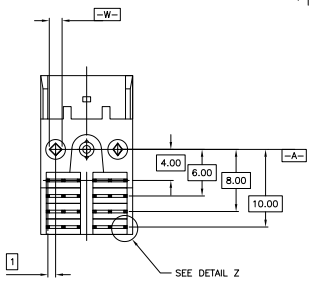
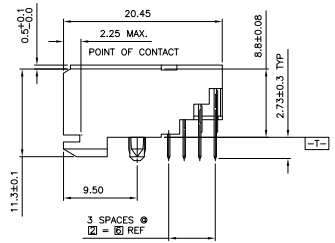
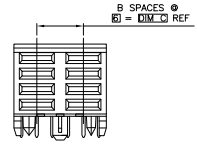
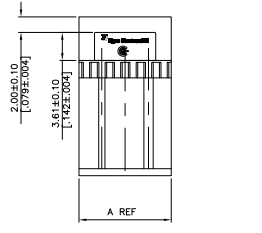


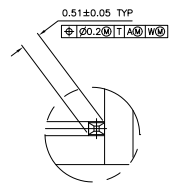
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REV	DATE	DESCRIPTION	BY	CHK	APP
AD	00	AS	REVISED PER EDD-11-004835	11MMR11	RK HMR



RECOMMENDED CIRCUIT PATTERN
 PER IPC-D350 TYPE II, CLASS C
 (COMPONENT SIDE)

- △ HOUSING MATERIAL: LIQUID CRYSTAL POLYMER.
- △ CONTACT MATERIAL: PHOSPHOR-BRONZE.
- △ CONTACT FINISH:(D)
- UNDERPLATE (ENTIRE CONTACT):
 0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290
- ON MATING SURFACES:
 FLASH GOLD PER ASTM B 488, OVER
 0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR
 0.00076 MIN GOLD [ER-ASTM B 488 OVER UNDERPLATE.
- ON LEADS:
 0.00381 MIN MATTE TIN PER ASTM B 545 OVER UNDERPLATE.
- LUBRICATION (MIN MATING SURFACES):
 SURFACE CONDITIONER AFTER PLATING.



DETAIL Z
 SCALE 20:1

10	5	6	1	11.88	8	5536607-1
E	D	C	B	A	FINISH	PART NUMBER
THIS DRAWING IS A CONTROLLED DOCUMENT.						
DRAWING LEVEL:			DESIGNER:		TE Connectivity	
PROJECT FILE:			HEADER:		Z-PACK 2mm FB, POWER MODULE, RCPT. ASSY.	
OPERATION SPEC:			SPEC:		4 ROW, 2.73 mm LEAD LENGTH	
REV:			SIZE:		A1 00779 Q=5536607	
CUSTOMER DRAWING:			DATE:		1 1 1	